

深圳市正大升化工有限公司

henzhen Zhengdasheng Chemical. Co. Ltd

Product Manual

Epoxy Resin ZDS3230AB-10

1. Use description

Epoxy resin 3230AB-10 is an epoxy resin glue cured under normal temperature and low temperature conditions. It has anti-yellowing, strong adhesion, good fluidity, natural defoaming, small heat generation after mixing, greenhouse curing or heat curing; **The thickness is 10-15CM, there is no requirement for the mixing quantity**; it is dedicated to the insulation of large pieces of crafts, jewelry, and electronic potting and mold filling and other electronic parts, moisture-proof potting, secret sealing and so on. 15CM 5-6 hours curing 12-16 hours can be demoulded.

Tip:

1. If it is used to contact food after curing, the temperature of the food should not exceed 50 degrees Celsius.

2. When the hardness is higher than 82D (Shaw hardness), it can be directly polished. If the hardness does not exceed 82D, use the ZDS-400-4ab Coating product and sand/polish it.

2. Hardening properties:

	Epoxy 3230A-10	Harder3230B-10
Color:	Colorless and transparent	
Proportion:	1.15	0.96
Viscosity 25°C:	<u>1200-1500CPS</u>	<u>500-800MAXCPS</u>

3. Conditions of Use:

- 1) Ratio: A: B=100: 33 (weight ratio)
A: B=100: 50 (volume ratio)
- 2) Hardening conditions: **25°C×10H-20H(100) or 55°C×2.5H(2g)**
- 3) Pot life: **25°C×40min(100g)**

4. Use method:

1. Working environment: keep the plastic container clean. A and B components are strictly weighed according to the weight ratio. Weigh accurately. Stir well along the inner wall of the container and then let it stand for 3-5 minutes.

PS: Resin and Hardener are forbidden to eat under liquid state. Our company will not be responsible for any illegal operation.

2. According to the operation time and dosage, adjust the amount of glue to avoid waste. When the temperature is lower than 15 ° C, please preheat the A glue to 30 ° C before adjusting the glue, which is easy to operate (A glue will thicken when the temperature is low); the barrel lid must be sealed after use to avoid product scrapping due to moisture absorption.

3. When the relative humidity is greater than 85%, the surface of the cured product easily absorbs moisture in the air to form a white mist. Therefore, when the relative humidity is greater than 85%, it is not suitable for curing at room temperature. It is recommended to use warm curing.

4. It is necessary to seal the lid after use to avoid product reports due to moisture absorption.

5. If it is to be ground, it needs to be 3 days after it is fully cured.

5. Hardened property:

1) Hardness:	shore D	<80
2) Withstand voltage:	KV/mm	22
3) Bending strength:	Kg/mm ²	28
4) Volume resistance:	Ohm ³	1x10*15
5) Surface resistance:	Ohm ²	5X10*15
6) Thermal conductivity:	W/M.K	1.36
7) Lure power loss:	1KHZ	0.42
8) Heat distortion temperature:	°C	80
9) Water absorption:	%	<0.15
10) Compressive strength:	Kg/mm ²	8.4

The above performance data is typical data measured in a laboratory environment with a temperature of 25°C and a humidity of 70%. It is for customer reference only.

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